



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



APPROVAL SHEET

RFBPB 2012(0805) Series – RoHS Compliance

MULTILAYER CERAMIC BAND PASS FILTER
- Balanced Type

Halogens Free Product

2.4 GHz ISM Band Working Frequency

P/N: RFBPB2012090A9T

*Contents in this sheet are subject to change without prior notice.

Approval sheet

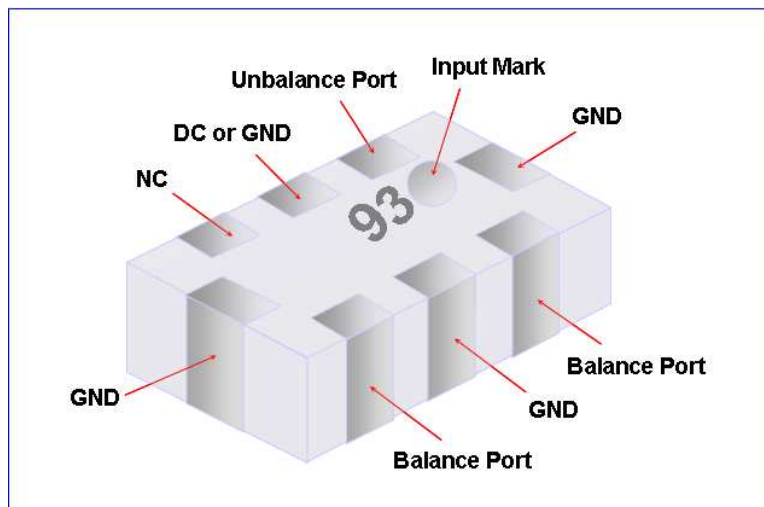
FEATURES

1. Miniature footprint: 2.0 X 1.2 X 0.9 mm³
2. Low Profile Thickness
3. Low Insertion loss
4. High Rejection Rate
5. High attenuation on 2nd harmonic suppressed
6. Allowable for DC biasing.
7. LTCC process

APPLICATIONS

1. 2.4GHz ISM band RF applications
2. Bluetooth, Wireless LAN 802.11b/g/n, HomeRF

CONSTRUCTION



DIMENSIONS

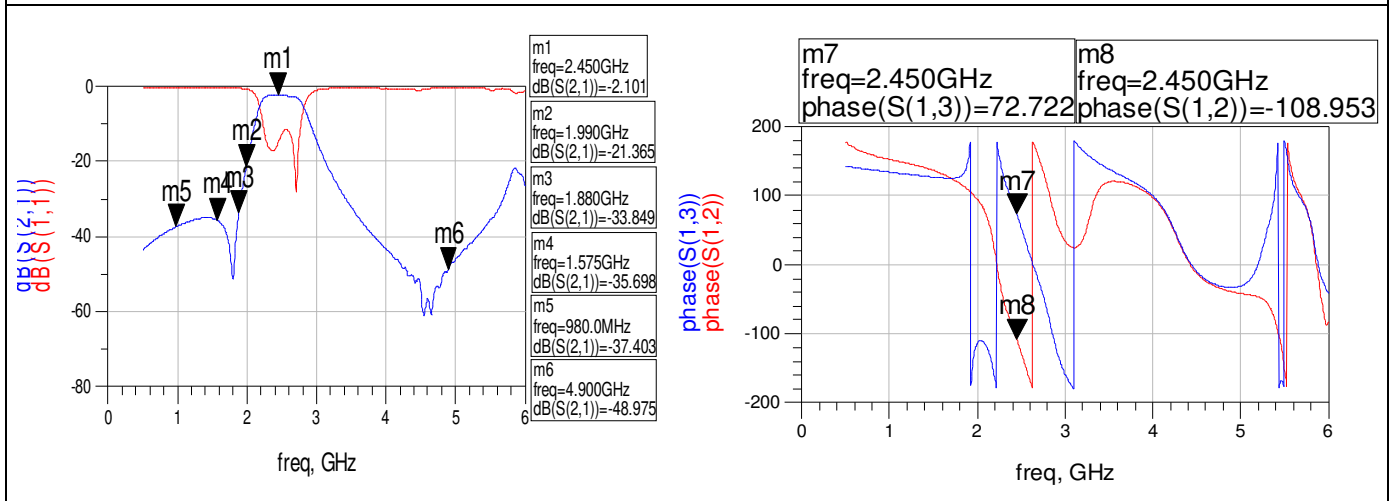
Figure	Symbol	Dimension (mm)
<p>The figure shows three views of the component: a top view, a side view, and a cross-sectional view. The top view shows a rectangular footprint with dimensions L (length) and W (width). A central circular mark is shown. The side view shows the thickness T. The cross-sectional view shows the internal structure with layers labeled A, B, C, D, E, F, and G. Dimensions A through G are indicated with arrows.</p>	L	2.0 0± 0.15
	W	1.25 ± 0.10
	T	0.90±0.10
	A	0.20 ± 0.15
	B	0.30 ± 0.10
	C	0.35 ± 0.10
	D	0.65 ± 0.10
	E	0.20 ± 0.15
	F	0.20 ± 0.15
	G	0.30 ± 0.10

Approval sheet

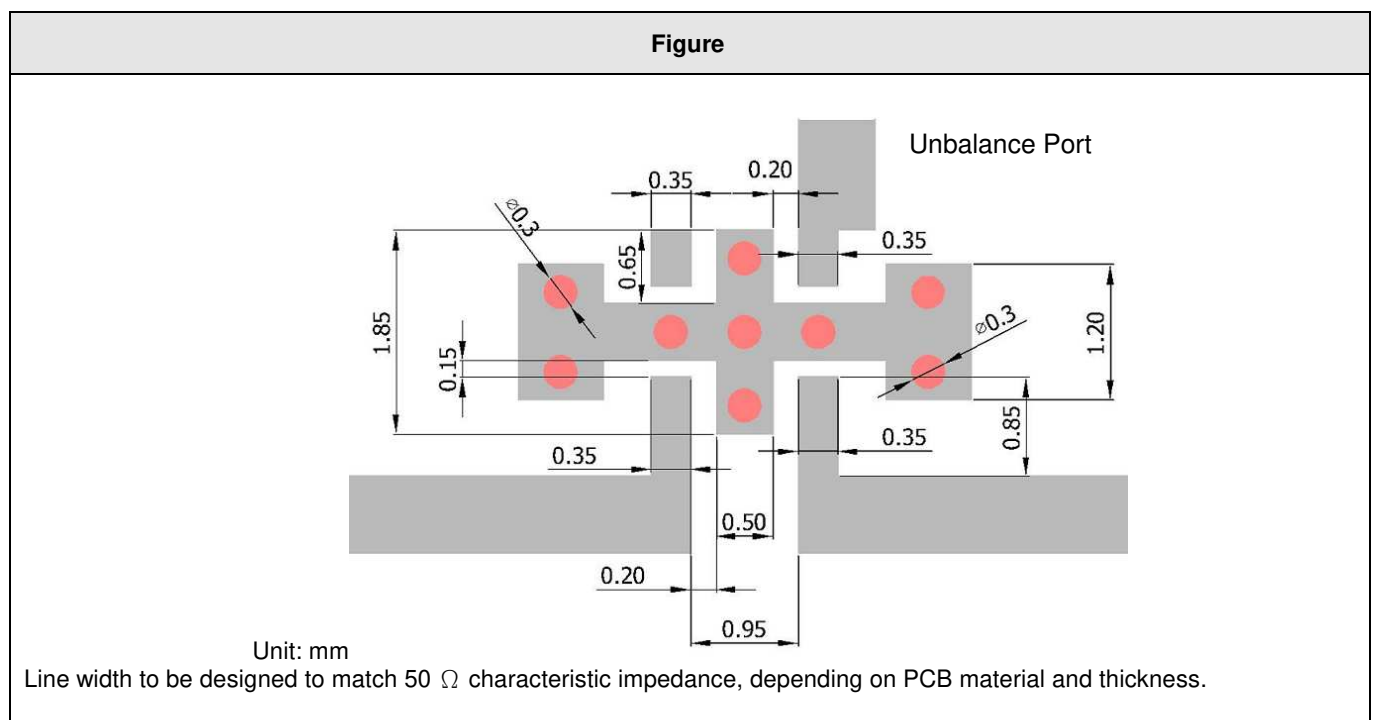
ELECTRICAL CHARACTERISTICS

RFBPB2012090A9T	Specification
Frequency range	2450 ± 50 MHz
Insertion Loss	2.8 dB max
VSWR	2.1 max
Impedance (Unbalanced)	50 Ω
Impedance (Balanced)	Conjugate match to BC series of Bluetooth chipset
Phase Difference	180° ± 10°
Amplitude Difference	2.0 dB Max
Attenuation (min.)	35dB @ 880~960 MHz 30dB @ 1575 MHz 25dB @ 1710~1880 MHz 30dB @ 4800~5000 MHz

Typical Electrical Chart



SOLDER LAND PATTERN



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RELIABILITY TEST

Test item	Test condition / Test method	Specification
Solderability JIS C 0050-4.6 JESD22-B102D	*Solder bath temperature : $235 \pm 5^{\circ}\text{C}$ *Immersion time : 2 ± 0.5 sec *Solder : Sn3Ag0.5Cu for lead-free	At least 95% of a surface of each terminal electrode must be covered by fresh solder.
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : 30 ± 0.5 sec *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : $120\sim 150^{\circ}\text{C}$, 1 minute. *Solder temperature : $270\pm 5^{\circ}\text{C}$ *Immersion time : 10 ± 1 sec *Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24 ± 2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test. Loss of metallization on the edges of each electrode shall not exceed 25%.
Drop Test JIS C 0044	*Height : 75 cm *Test Surface : Rigid surface of concrete or steel. *Times : 6 surfaces for each units : 2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force : $5\text{N}(\leq 0603)$; $10\text{N}(>0603)$ *Test time : 10 ± 1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5 ± 1 sec. Measurement to be made after keeping at room temperature for 24 ± 2 hours	No mechanical damage. Samples shall satisfy electrical specification after test.

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Temperature cycle JIS C 0025	<ol style="list-style-type: none"> 1. 30±3 minutes at -40°C±3°C, 2. 10~15 minutes at room temperature, 3. 30±3 minutes at +85°C±3°C, 4. 10~15 minutes at room temperature, <p>Total 100 continuous cycles Measurement to be made after keeping at room temperature for 24±2 hrs</p>	<p>No mechanical damage. Samples shall satisfy electrical specification after test.</p>
Vibration JIS C 0040	<p>*Frequency : 10Hz~55Hz~10Hz(1min) *Total amplitude : 1.5mm *Test times : 6hrs.(Two hrs each in three mutually perpendicular directions)</p>	<p>No mechanical damage. Samples shall satisfy electrical specification after test.</p>
High temperature JIS C 0021	<p>*Temperature : 85°C±2°C *Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs</p>	<p>No mechanical damage. Samples shall satisfy electrical specification after test.</p>
Humidity (steady conditions) JIS C 0022	<p>*Humidity : 90% to 95% R.H. *Temperature : 40±2°C *Time : 1000+24/-0 hrs. Measurement to be made after keeping at room temperature for 24±2 hrs ※ 500hrs measuring the first data then 1000hrs data</p>	<p>No mechanical damage. Samples shall satisfy electrical specification after test.</p>
Low temperature JIS C 0020	<p>*Temperature : -40°C±2°C *Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs</p>	<p>No mechanical damage. Samples shall satisfy electrical specification after test.</p>

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SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

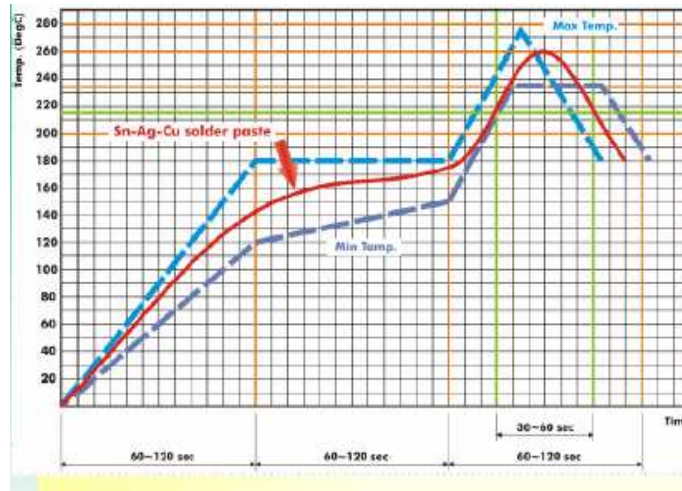


Fig 2. Infrared soldering profile

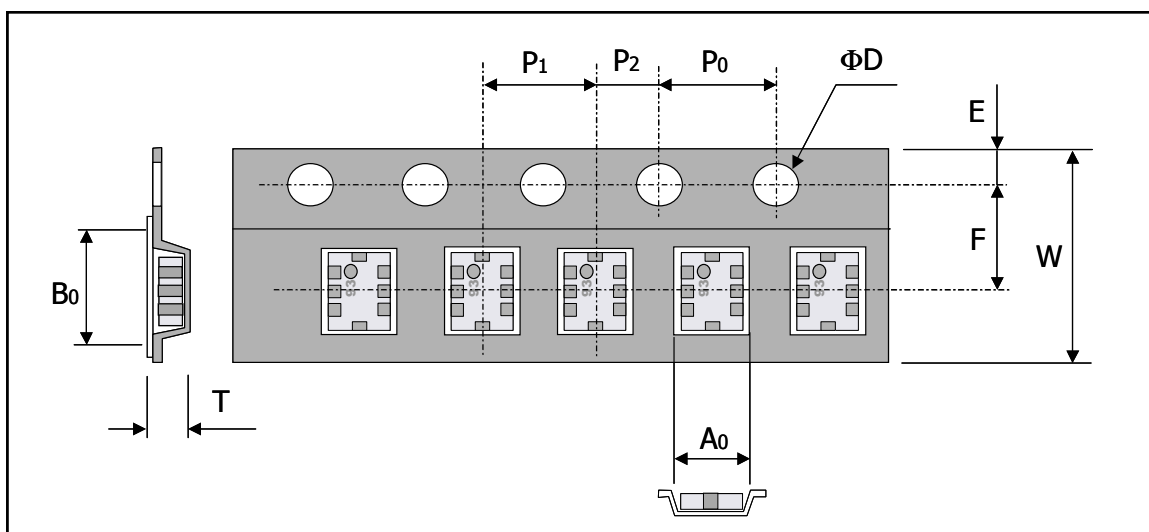
ORDERING CODE

RF Walsin RF device	BPB Product Code BPB : Balanced Type Band Pass Filter	201209 Dimension code Per 2 digits of Length, Width, Thickness : e.g. : 201209 = Length 20, Width 12, Thickness 0.9	0 Unit of dimension 0 : 0.1 mm 1 : 1.0 mm	A Application A : 2.4GHZ ISM Band	9 Specification Design Code	T Packing T: 7" Reeled
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Minimum Ordering Quantity: 2000 pcs per reel.

By 7" Reeled package

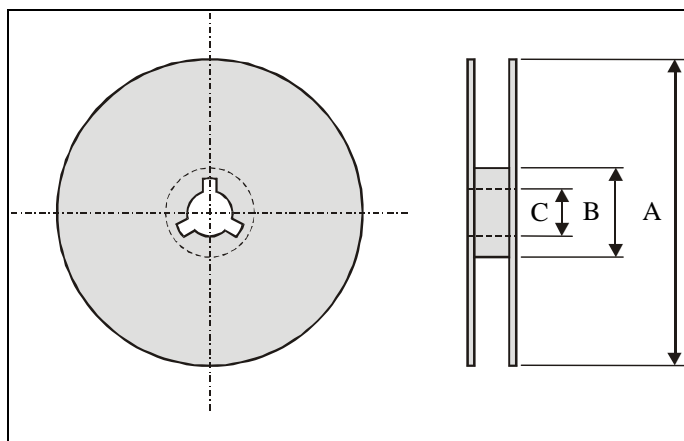
PACKAGING



Plastic Tape specifications (unit :mm)

Index	Ao	Bo	ΦD	T	W
Dimension (mm)	1.35 ± 0.10	2.30 ± 0.10	1.55 ± 0.10	0.95 ± 0.10	8.00 ± 0.30
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10

Reel dimensions



Index	A	B	C
Dimension (mm)	Φ178	Φ60.0	Φ13.5

Typing Quantity: 2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WAL SIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.
 - Temperature : -10 to +40°C
 - Humidity : 30 to 70% relative humidity
 - Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
 - Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
 - Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
 - Products should be storage under the airtight packaged condition.